

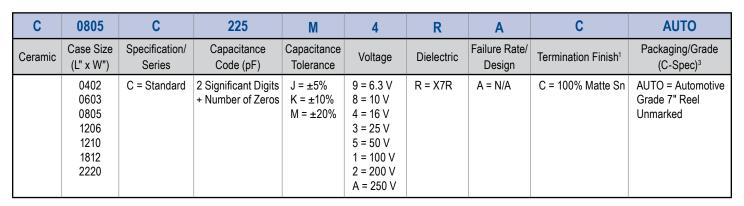
#### **Overview**

KEMET's Automotive Grade Series surface mount capacitors in X7R dielectric are suited for a variety of applications requiring proven, reliable performance in harsh environments. Whether under-hood or in-cabin, these devices emphasize the vital and robust nature of capacitors required for mission and safety critical automotive circuits. Stricter testing protocol and inspection criteria have been established for automotive grade products in recognition of potentially harsh environmental conditions . KEMET automotive grade series capacitors meet the demanding Automotive Electronics Council's AEC–Q200 qualification requirements X7R dielectric features a 125°C maximum operating temperature and is considered "temperature stable," The Electronics Industries Alliance (EIA) characterizes X7R dielectric as a Class II material. Components of this classification are fixed, ceramic dielectric capacitors suited for bypass and decoupling applications or for frequency discriminating circuits where Q and stability of capacitance characteristics are not critical. X7R exhibits a predictable change in capacitance with respect to time and voltage and boasts a minimal change in capacitance with reference to ambient temperature. Capacitance change is limited to  $\pm 15\%$  from -55°C to +125°C.

# **Benefits**

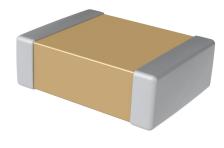
- · AEC-Q200 automotive qualified
- -55°C to +125°C operating temperature range
- · Lead (Pb)-Free, RoHS and REACH compliant
- Temperature stable dielectric
- EIA 0402, 0603, 0805, 1206, 1210, 1812, and 2220, case sizes
- DC voltage ratings of 6.3 V, 10 V, 16 V, 25 V, 50 V, 100 V, 200 V, and 250 V
- Capacitance offerings ranging from 10 pF to 22  $\mu F$
- Available capacitance tolerances of ±5%, ±10%, and ±20%
- · Non-polar device, minimizing installation concerns
- 100% pure matte tin-plated termination finish allowing for excellent solderability

# **Ordering Information**



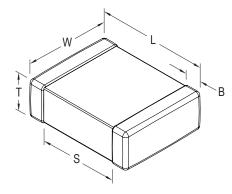
<sup>1</sup> Additional termination finish options may be available. Contact KEMET for details

<sup>2</sup>Additional reeling or packaging options may be available. Contact KEMET for details.





### **Dimensions – Millimeters (Inches)**



EIA Size Code	Metric Size Code	L Length	W Width	T Thickness	B Bandwidth	S Separation Minimum	Mounting Technique
0402	1005	1.00 (.040) ± 0.05 (.002)	0.50 (.020) ± 0.05 (.002)		0.30 (.012) ± 0.10 (.004)	0.30 (.012)	Solder Reflow Only
0603	1608	1.60 (.063) ± 0.15 (.006)	0.80 (.032) ± 0.15 (.006)		0.35 (.014) ± 0.15 (.006)	0.70 (.028)	
0805	2012	2.00 (.079) ± 0.20 (.008)	1.25 (.049) ± 0.20 (.008)		0.50 (0.02) ± 0.25 (.010)	0.75 (.030)	Solder Wave or Solder Reflow
1206	3216	3.20 (.126) ± 0.20 (.008)	1.60 (.063) ± 0.20 (.008)	See Table 2 for Thickness	0.50 (0.02) ± 0.25 (.010)		
1210 <sup>1</sup>	3225	3.20 (.126) ± 0.20 (.008)	2.50 (.098) ± 0.20 (.008)		0.50 (0.02) ± 0.25 (.010)	N1/A	
1812	4532	4.50 (.177) ± 0.30 (.012)	3.20 (.126) ± 0.30 (.012)		0.60 (.024) ± 0.35 (.014)	N/A	Solder Reflow Only
2220	5650	5.70 (.224) ± 0.40 (.016)	5.00 (.197) ± 0.40 (.016)		0.60 (.024) ± 0.35 (.014)		

<sup>1</sup> For capacitance values  $\geq$  12  $\mu$ F add 0.02 (0.001) to the width tolerance dimension

# **Applications**

Typical applications include decoupling, bypass, filtering and transient voltage suppression.

# **Qualification/Certification**

Automotive Grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC–Q200, Stress Test Qualification for Passive Components. For additional information regarding the Automotive Electronics Council and AEC–Q200, please visit their website at www.aecouncil.com.



# **Environmental Compliance**

Lead (Pb)-Free, RoHS, and REACH compliant without exemptions (excluding SnPb termination finish option).



# **Electrical Parameters/Characteristics**

Item	Parameters/Characteristics
Operating Temperature Range	-55°C to +125°C
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	±15%
Aging Rate (Maximum % Capacitance Loss/Decade Hour)	3.0%
Dielectric Withstanding Voltage (DWV)	250% of rated voltage (5 ±1 seconds and charge/discharge not exceeding 50 mA)
Dissipation Factor (DF) Maximum Limit @ 25°C	5% (6.3 and 10 V), 3.5% (16 and 25 V) and 2.5% (50 to 250 V)
Insulation Resistance (IR) Limit @ 25°C	See Insulation Resistance Limit Table (Rated voltage applied for 120 ±5 seconds @ 25°C)

Regarding aging rate: Capacitance measurements (including tolerance) are indexed to a referee time of 1,000 hours.

To obtain IR limit, divide  $M\Omega$ - $\mu$ F value by the capacitance and compare to  $G\Omega$  limit. Select the lower of the two limits.

Capacitance and dissipation factor (DF) measured under the following conditions:

1 kHz ±50 Hz and 1.0 ±0.2 Vrms if capacitance  $\leq$  10  $\mu$ F

120 Hz ±10 Hz and 0.5 ±0.1 Vrms if capacitance >10  $\mu$ F

Note: When measuring capacitance it is important to ensure the set voltage level is held constant. The HP4284 and Agilent E4980 have a feature known as Automatic Level Control (ALC). The ALC feature should be switched to "ON."

# **Post Environmental Limits**

	High Temperatu	ıre Life, Biased	Humidity, Moist	ture Resistance	•
Dielectric	Rated DC Voltage	Capacitance Value	Dissipation Factor (Maximum %)	Capacitance Shift	Insulation Resistance
	> 25		3.0		
X7R	16/25	All	5.0	±20%	10% of Initial Limit
	< 16		7.5		



# **Insulation Resistance Limit Table**

EIA Case Size	1,000 Megohm Microfarads or 100 GΩ	500 Megohm Microfarads or 10 GΩ
0201	N/A	ALL
0402	< 0.012 µF	≥ 0.012 µF
0603	< 0.047 µF	≥ 0.047 µF
0805	< 0.15 µF	≥ 0.15 µF
1206	< 0.47 µF	≥ 0.47 µF
1210	< 0.39 µF	≥ 0.39 µF
1808	ALL	N/A
1812	< 2.2 µF	≥ 2.2 µF
1825	ALL	N/A
2220	< 10 µF	≥ 10 µF
2225	ALL	N/A



# Table 1A – Capacitance Range/Selection Waterfall (0402 – 1206 Case Sizes)

			se S Serie			CO	402	2C				С	)60:	3C					(	208	05C	;					(	C12	060	;		
Capacitance	Сар	Volt	age C	ode	9	8	4	3	5	9	8	4	3	5	1	2	9	8	4	3	5	1	2	A	9	8	4	3	5	1	2	Α
oupuonunee	Code		ed Vol (VDC)		6.3	10	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	250	6.3	10	16	25	50	100	200	250
			acita oleran			Pro	duc	t Av	aila	bili	ty a	nd	Chip	o Th	ick	nes	s Co	ode	s – S	See	Tab	le 2	for	Ch	ip T	hicl	knes	ss D	ime	ensi	ons	
10 - 91 pF*	100 - 910*	J	K	M	BB	BB	BB	BB	BB	CF	DC		EB	EB	EB	EB	EB	EB	EB													
100 - 150 pF**	101 - 151**	J	K	M	BB	BB	BB	BB	BB	CF	DC	-	EB	EB	EB	EB	EB	EB	EB													
180 - 820 pF** 1,000 pF	181 - 821** 102	J	K K	M	BB BB	BB BB	BB BB	BB BB	BB BB	CF CF	DC DC		EB EB	EB EB	EB EB	EB EB	EB EB	EB EB	EB													
1,200 pF	102	J	K	M	BB	BB	BB	BB	BB	CF	DC	EB	EB	EB	EB	EB	EB	EB	EB													
1,500 pF	152	J	K	M	BB	BB	BB	BB	BB	CF	DC		EB	EB	EB	EB	EB	EB	EB													
1,800 pF	182	J	ĸ	M	BB	BB	BB	BB	BB	CF	DC	EB	EB	EB	EB	EB	EB	EB	EB													
2,200 pF	222	J	К	М	BB	BB	BB	BB	BB	CF	DC	EB	EB	EB	EB	EB	EB	EB	EΒ													
2,700 pF	272	J	К	M	BB	BB	BB	BB	BB	CF	DC	EB	EB	EB	EB	EB	EB	EB	EB													
3,300 pF	332	J	Κ	M	BB	BB	BB	BB	BB	CF	DC	EB	EB	EB	EB	EB	EB	EB	EB													
3,900 pF	392	J	K	M	BB	BB	BB	BB	BB	CF	DC	EB	EB	EB	EB	EB	EB	EB	EB													
4,700 pF	472	J	K	M	BB	BB	BB	BB	BB	CF	DC		EB	EB	EB	EB	EB	EB	EB													
5,600 pF	562	J	K	M	BB	BB	BB	BB	BB	CF	DC	EB	EB	EB	EB	EB	EB	EB	EB													
6,800 pF	682	J	K	M	BB	BB	BB	BB	BB	CF	DC		EB	EB	EB	EB	EB	EB	EB													
8,200 pF	822	J	K	M	BB BB	BB	BB BB	BB BB	BB BB	CF CF	DC DC	DC	DC DC	DC DC	DC DC	DC DC	DC DC	DC DC	EB EB	EB	EB EB	EB EB	EB EB	EB EB	EB EB	EB EB						
10,000 pF 12,000 pF	103 123	J	K K	M	BB	BB BB	вв BB	BB	вв	CF	CF	CF	CF	CF	CF	UF	DC	DC DC	DC	DC	DC	DC	DC	DC	EB	EB EB	EB	EB	EB	EB	EB	EB
15,000 pF	123	J	K	M	BB	BB	BB	BB	BB	CF	CF	CF	CF	CF	CF		DC	DC	DC	DC	DC	DD	DC	DC		EB	EB	EB	EB	EB	EB	EB
18,000 pF	183	J	ĸ	M	BB	BB	BB	BB	BB	CF	CF	CF	CF	CF	CF		DC	DC	DC	DC	DC	DD	DC	DC	EB	EB	EB	EB	EB	EB	EB	EB
22,000 pF	223	Ĵ	ĸ	M	BB	BB	BB	BB	BB	CF	CF	CF	CF	CF	CF		DC	DC	DC	DC	DC	DD	-	DC		EB	EB	EB	EB	EB	EB	EB
27,000 pF	273	J	K	М	BB	BB	BB	BB		CF	CF	CF	CF	CF	CF		DC	DC	DC	DC	DC	DD	DE		EB	EB	EB	EB	EB	EB	EB	EB
33,000 pF	333	J	К	М	BB	BB	BB	BB		CF	CF	CF	CF	CF	CF		DC	DC	DC	DC	DC	DD	DE		EB	EB	EB	EB	EB	EB	EB	ΕB
39,000 pF	393	J	К	M	BB	BB	BB	BB		CF	CF	CF	CF	CF	CF		DC	DC	DC	DC	DC	DD	DE		EB	EB	EB	EB	EB	EC	EB	EΒ
47,000 pF	473	J	Κ	M	BB	BB	BB	BB		CF	CF	CF	CF	CF	CF		DC	DC	DC	DC	DC	DE	DG		EB	EB	EB	EB	EB	EC	ED	ED
56,000 pF	563	J	K	M	BB	BB	BB			CF	CF	CF	CF	CF			DD	DD	DD	DD	DD	DE	DG		EB	EB	EB	EB	EB	EB	ED	ED
68,000 pF	683	J	K	M	BB	BB	BB			CF	CF	CF	CF	CF			DD	DD	DD	DD	DD	DE			EB	EB	EB	EB	EB	EB	ED	ED
82,000 pF	823	J	K	M	BB	BB	BB			CF	CF	CF	CF	CF			DD	DD	DD	DD	DD	DE			EB	EB	EB	EB	EB	EB	ED	ED
0.10 μF 0.12 μF	104	J	K	M	BB	BB	BB			CF CF	CF CF	CF CF	CF CF	CF CF			DC DC	DC	DC DC	DC DC	DC DD	DE DG			EB EC	EB	EB EC	EB EC	EB EC	EB EC	EM EG	EM
0.12 μF 0.15 μF	124 154	J	K K	M						CF	CF	CF	CF	CF			DC	DC DC	DC	DC	DD	DG			EC	EC EC	EC	EC	EC	EC	EG	
0.13 µF	184	J	K	M						CF	CF	CF	CF	UI.			DC	DC	DC	DC	DD	DG			EC	EC	EC	EC	EC	EC	LG	
0.22 µF	224	J	ĸ	M						CF	CF	CF	CF				DC	DC	DC	DC	DD	DG			EC	EC	EC	EC	EC	EC		
0.27 µF	274	J	ĸ	M						CF	CF	CF	0.				DD	DD	DD	DD	DD				EB	EB	EB	EB	EC	EM		
0.33 µF	334	J	К	М	1					CF	CF	CF					DD	DD	DD	DD	DD				EB	EB	EB	EB	EC	EG		
0.39 µF	394	J	К	M	1					CF	CF	CF					DG	DG	DG	DG	DE				EB	EB	EB	EB	EC	EG		
0.47 µF	474	J	К	Μ						CF	CF	CF					DD	DD	DD	DD	DE				EC	EC	EC	EC	EC	EG		
0.56 µF	564	J	к	M													DD	DD	DD	DG	DH				ED	ED	ED	ED	EC			
0.68 µF	684	J	К	M													DD	DD	DD	DG	DH				EE	EE	EE	EE	ED			
0.82 µF	824	J	K	M													DD	DD	DD	DG					EF	EF	EF	EF	ED			
1.0 µF	105	J	K	M															DD	DG					EF	EF		EG				
1.2 µF	125	J	K	M														DE							ED	ED	ED					
1.5 μF 1.8 μF	155 185	J	K K	M													DG	DG DG	DG						EF ED	EF ED	EF ED	EG EF				
2.2 μF	225	.1	K	M														DG							ED	ED	ED	EH				
2.2 μ1 2.7 μF	275	J	K	M													00	00	00								EN					
3.3 µF	335	J	K	M																					ED	ED	ED					
3.9 µF	395	J	К	М																						EF		EH				
			d Vol (VDC)		6.3	9	16	25	50	6.3	9	16	25	50	100	200	6.3	9	9	25	50	100	200	250	6.3	9	16	25	50	<del>1</del> 0	200	250
Capacitance	Cap Code	Volt	age C	ode	9	8	4	3	5	9	8	4	3	5	1	2	9	8	4	3	5	1	2	A	9	8	4	3	5	1	2	A
	0000		se S Serie			С	)402	2C				C	0603	BC						C08	05C					s		C12	060	;		

\*Capacitance range includes E24 decade values only. (i.e., 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 30, 33, 36, 39, 43, 47, 51, 56, 62, 68, 75, 82 and 91) \*\*Capacitance range includes E12 decade values only. (i.e., 10, 12, 15, 18, 22, 27, 33, 39, 47, 56, 68 and 82)



### Table 1A – Capacitance Range/Selection Waterfall (0402 – 1206 Case Sizes) cont'd

			se S Seri	Size es		C	)40	2 <b>C</b>				C	)60:	3C					(	208	050	;					(	C12	060	;		
Capacitance	Сар	Vol	tage	Code	9	8	4	3	5	9	8	4	3	5	1	2	9	8	4	3	5	1	2	Α	9	8	4	3	5	1	2	Α
Capacitance	Code	Rat	ed Vo (VDC	ltage ;)	6.3	9	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	250	6.3	10	16	25	50	100	200	250
			pacita olera			Pro	duc	t Av	/aila	abili	ty a	nd(	Chip	o Th	ickı	nes	s Co	odes	s – S	See	Tab	le 2	for	Ch	ір Т	hick	nes	s D	ime	nsi	ons	
4.7 µF	475	J	K	М																					EF	EF	EF	EH				
5.6 µF	565	J	K	M																					EH	EH	EH					
6.8 µF	685	J	K	M																					EH	EH	EH					
8.2 µF	825	J	K	M																					EH	EH	EH					
10 µF	106	J	K	M																					EH	EH	EH					
		Rat	ed Vo (VDC	ltage ;)	6.3	10	16	25	50	6.3	10	16	25	50	100	200	6.3	10	16	25	50	100	200	250	6.3	10	16	25	50	100	200	250
Capacitance	Cap Code	Vol	tage	Code	9	8	4	3	5	9	8	4	3	5	1	2	9	8	4	3	5	1	2	A	9	8	4	3	5	1	2	Α
			ise S Seri	Size es		C	0402	2C				C	0603	BC						C08	05C	;						C12	06C			

\*Capacitance range includes E24 decade values only. (i.e., 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 30, 33, 36, 39, 43, 47, 51, 56, 62, 68, 75, 82 and 91) \*\*Capacitance range includes E12 decade values only. (i.e., 10, 12, 15, 18, 22, 27, 33, 39, 47, 56, 68 and 82)

### Table 1B – Capacitance Range/Selection Waterfall (1210 – 2220 Case Sizes)

			ise S Serie					C12	210C					С	1812	2C			C18	25C			C	2220	C	
Capacitance	Сар	Vol	tage C	ode	9	8	4	3	5	1	2	A	3	5	1	2	A	5	1	2	A	3	5	1	2	A
Capacitance	Code	Rat	ed Vol (VDC)		6.3	10	16	25	50	100	200	250	25	50	100	200	250	50	100	200	250	25	50	100	200	250
			pacita oleran		Pi	rodu	ct Av	vaila	bility	and	Chij	o Thi	ckne	ess C	ode	s – S	ee Ta	able	2 for	<sup>.</sup> Chi	p Thi	ickne	ess C	)ime	nsio	ns
10 - 91 pF*	100 - 910*	J	K	M	FB	FB	FB	FB	FB	FB	FB															
100 - 390 pF**	101 - 391**	J	K	M	FB	FB	FB	FB	FB	FB	FB															
470 - 820 pF**	471 - 821**	J	K	M	FB	FB	FB	FB	FB	FB	FB		GB	GB	GB	GB										
1,000 pF	102	J	K	M	FB	FB	FB	FB	FB	FB	FB		GB	GB	GB	GB										
1,200 pF	122	J	K	M	FB	FB	FB	FB	FB	FB	FB		GB	GB	GB	GB										
1,500 pF	152	J	K	M	FB	FB	FB	FB	FB	FB	FE		GB	GB	GB	GB										
1,800 pF	182	J	K	M	FB	FB	FB	FB	FB	FB	FE		GB	GB	GB	GB										
2,200 pF	222	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB										
2,700 pF	272	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB										
3,300 pF	332	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB										
3,900 pF	392	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB										
4,700 pF	472	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GD										
5,600 pF	562	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GH										
6,800 pF	682	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB					JE	JE	JE		
8,200 pF	822	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB					JE	JE	JE		
10,000 pF	103	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB					JE	JE	JE		
12,000 pF	123	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB					JE	JE	JE		
15,000 pF	153	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB					JE	JE	JE		
18,000 pF	183	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB					JE	JE	JE		
		Rat	ed Vol (VDC)		6.3	10	16	25	50	100	200	250	25	50	100	200	250	50	100	200	250	25	50	100	200	250
Capacitance	Cap Code	Vol	tage C	ode	9	8	4	3	5	1	2	A	3	5	1	2	Α	5	1	2	A	3	5	1	2	Α
	Code		ise S Serie					C12	210C			•		С	1812	C			C18	25C			С	2220	С	

\*Capacitance range includes E24 decade values only. (i.e., 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 30, 33, 36, 39, 43, 47, 51, 56, 62, 68, 75, 82 and 91) \*\*Capacitance range includes E12 decade values only. (i.e., 10, 12, 15, 18, 22, 27, 33, 39, 47, 56, 68 and 82)



# Table 1B – Capacitance Range/Selection Waterfall (1210 – 2220 Case Sizes) cont'd

			ise S Serie					C12	10C					С	1812	2C			C18	25C			С	222(	C	
Capacitance	Сар	Vol	tage C	ode	9	8	4	3	5	1	2	A	3	5	1	2	A	5	1	2	A	3	5	1	2	Α
oupuonunoo	Code	Rat	ed Vol (VDC)		6.3	10	16	25	50	100	200	250	25	50	100	200	250	50	100	200	250	25	50	100	200	250
			pacita oleran		Pr	odu	ct Av	ailal	bility	and	Chip	o Thi	ckne	ess C	ode	s – S	ee Ta	able	2 foi	<sup>.</sup> Chi	p Th	ickne	ess [	Dime	nsio	ns
22,000 pF	223	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB	HB	HB	HB	HB	JE	JE	JE		
27,000 pF	273	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB	HB	HB	HB	HB	JE	JE	JE		
33,000 pF	333	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB	HB	HB	HB	HB	JB	JB	JB		
39,000 pF	393	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB	HB	HB	HB	HB	JB	JB	JB		
47,000 pF	473	J	K	M	FB	FB	FB	FB	FB	FB	FB	FB	GB	GB	GB	GB	GB	HB	HB	HB	HB	JB	JB	JB		
56,000 pF	563	J	K	M	FB	FB	FB	FB	FB	FB	FC	FC	GB	GB	GB	GB	GB	HB	HB	HB	HB	JB	JB	JB		
68,000 pF	683	J	K	M	FB	FB	FB	FB	FB	FB	FC	FC	GB	GB	GB	GB	GB	HB	HB	HB	HB	JB	JB	JB		
82,000 pF	823	J	K	M	FB	FB	FB	FB	FB	FC	FF	FF	GB	GB	GB	GB	GB	HB	HB	HB	HB	JB	JB	JC	JC	JC
0.10 µF	104	J	к	M	FB	FB	FB	FB	FB	FD	FG	FG	GB	GB	GB	GB	GB	ΗВ	HB	HB	HB	JB	JB	JC	JC	JC
0.12 µF	124	J	к	M	FB	FB	FB	FB	FB	FD			GB	GB	GB	GB	GB	ΗВ	HB	HB	НВ	JB	JB	JC	JC	JC
0.15 µF	154	J	к	M	FC	FC	FC	FC	FC	FD			GB	GB	GB	GE	GE	ΗВ	HB	HB	НВ	JB	JB	JC	JC	JC
0.18 µF	184	J	K	М	FC	FC	FC	FC	FC	FD			GB	GB	GB	GG	GG	НВ	НВ	HB	HB	JB	JB	JC	JC	JC
0.22 µF	224	Ĵ	к	м	FC	FC	FC	FC	FC	FD			GB	GB	GB	GG	GG	НВ	НВ	НВ	НВ	JB	JB	JC	JC	JC
0.27 µF	274	J	K	M	FC	FC	FC	FC	FC	FD			GB	GB	GG	GG	GG	HB	HB	HB	HB	JC	JC	JC	JC	JC
0.33 µF	334	J	K	M	FD	FD	FD	FD	FD	FD			GB	GB	GG	GG	GG	HB	HB	HB	HB	JC	JC	JC	JC	JC
0.39 µF	394	J	K	M	FD	FD	FD	FD	FD	FD			GB	GB	GG	GG	GG	HD	HD	HD	HD	JC	JC	JC	JC	JC
0.47 µF	474	J	K	M	FD	FD	FD	FD	FD	FD			GB	GB	GG	GJ	GJ	HD	HD	HD	HD	JC	JC	JC	JC	JC
0.56 µF	564	J	K	M	FD	FD	FD	FD	FD	FF			GC	GC	GG			HD	HD	HD	HD	JC	JD	JD	JD	JD
0.68 µF	684	J	K	M	FD	FD	FD	FD	FD	FG			GC	GC	GG			HD	HD	HD	HD	JC	JD	JD	JD	JD
0.82 µF	824	J	K	M	FF	FF	FF	FF	FF	FL			GE	GE	GG			HF	HF	HF	HF	JC	JF	JF	JF	JF
1.0 µF	105	J	K	M	FH	FH	FH	FH	FH	FM			GE	GE	GG			HF	HF	HF	HF	JC	JF	JF	JF	JF
1.2 µF	125	J	K	M	FH	FH	FH	FH	FG													JC	JC			
1.5 µF	155	J	K	M	FH	FH	FH	FH	FG													JC	JC			
1.8 µF	185	J	K	M	FH	FH	FH	FH	FG													JD	JD			
2.2 µF	225	Ĵ	K	M	FJ	FJ	FJ	FJ	FG				GO	GO								JF	JF			
2.7 µF	275	J	K	M	FE	FE	FE	FG	FH					00												
3.3 µF	335	J	K	M	FF	FF	FF	FM	FM																	
3.9 µF	395	J	K	M	FG	FG	FG	FG	FK																	
4.7 μF	475	J	K	M	FC	FC	FC	FG	FS				GК	GK								JF	JF			
4.7 μi 5.6 μF	565	J	K	M	FF	FF	FF	FH	10																	
6.8 µF	685	J	K	M	FG	FG	FG	FM																		
8.2 µF	825	J	K	M	FH	FH	FH	FK																		
10 μF	106	J	K	M	FH	FH	FH	FS					GK									JF	JO			
15 µF	156	J	K	M				10														JO	00			
22 µF	226	J	K	M	FS	FS																JO				
pi	220		ed Vol		6.3	10	16	25	50	100	200	250	25	50	100	200	250	50	100	200	250	25 6	50	6	200	250
	Сар		(VDC)																							
Capacitance	Code		tage C		9	8	4	3	5	1	2	A	3	5	1	2	A	5	1	2	A	3	5	1	2	A
			ise S Serie					C12	10C					С	1812	C			C18	25C			С	2220	C	

\*Capacitance range includes E24 decade values only. (i.e., 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 30, 33, 36, 39, 43, 47, 51, 56, 62, 68, 75, 82 and 91) \*\*Capacitance range includes E12 decade values only. (i.e., 10, 12, 15, 18, 22, 27, 33, 39, 47, 56, 68 and 82)



# Table 2 – Chip Thickness/Packaging Quantities

Thickness	Case	Thickness ±	Paper G	Quantity	Plastic (	Quantity
Code	Size	Range (mm)	7" Reel	13" Reel	7" Reel	13" Reel
BB CF DC DD DE	0402 0603 0805 0805 0805	$\begin{array}{c} 0.50 \pm 0.05 \\ 0.80 \pm 0.07 \\ 0.78 \pm 0.10 \\ 0.90 \pm 0.10 \\ 1.00 \pm 0.10 \end{array}$	10,000 4,000 4,000 4,000 0	50,000 15,000 10,000 10,000 0	0 0 0 2,500	0 0 0 10,000
DG DH EB EC EN	0805 0805 1206 1206 1206	$\begin{array}{c} 1.25 \pm 0.15 \\ 1.25 \pm 0.20 \\ 0.78 \pm 0.10 \\ 0.90 \pm 0.10 \\ 0.95 \pm 0.10 \end{array}$	0 0 4,000 0 0	0 0 10,000 0 0	2,500 2,500 4,000 4,000 4,000	10,000 10,000 10,000 10,000 10,000 10,000
ED EE EF EM EG	1206 1206 1206 1206 1206	$\begin{array}{c} 1.00 \pm 0.10 \\ 1.10 \pm 0.10 \\ 1.20 \pm 0.15 \\ 1.25 \pm 0.15 \\ 1.60 \pm 0.15 \end{array}$	0 0 0 0 0	0 0 0 0	2,500 2,500 2,500 2,500 2,000	10,000 10,000 10,000 10,000 8,000
EH FB FC FD FE	1206 1210 1210 1210 1210 1210	$\begin{array}{c} 1.60 \pm 0.20 \\ 0.78 \pm 0.10 \\ 0.90 \pm 0.10 \\ 0.95 \pm 0.10 \\ 1.00 \pm 0.10 \end{array}$	0 0 0 0	0 0 0 0	2,000 4,000 4,000 4,000 2,500	8,000 10,000 10,000 10,000 10,000
FF FG FL FH FM	1210 1210 1210 1210 1210 1210	$\begin{array}{c} 1.10 \pm 0.10 \\ 1.25 \pm 0.15 \\ 1.40 \pm 0.15 \\ 1.55 \pm 0.15 \\ 1.70 \pm 0.20 \end{array}$	0 0 0 0	0 0 0 0	2,500 2,500 2,000 2,000 2,000	10,000 10,000 8,000 8,000 8,000 8,000
FJ FK FS NA NC	1210 1210 1210 1706 1706	$\begin{array}{c} 1.85 \pm 0.20 \\ 2.10 \pm 0.20 \\ 2.50 \pm 0.30 \\ 0.90 \pm 0.10 \\ 1.00 \pm 0.15 \end{array}$	0 0 0 0	0 0 0 0	2,000 2,000 1,000 4,000 4,000	8,000 8,000 4,000 10,000 10,000
LD LF GB GC GD	1808 1808 1812 1812 1812 1812	$\begin{array}{c} 0.90 \pm 0.10 \\ 1.00 \pm 0.15 \\ 1.00 \pm 0.10 \\ 1.10 \pm 0.10 \\ 1.25 \pm 0.15 \end{array}$	0 0 0 0	0 0 0 0	2,500 2,500 1,000 1,000 1,000	10,000 10,000 4,000 4,000 4,000
GE GH GG GK GJ	1812 1812 1812 1812 1812 1812	1.30 ± 0.10 1.40 ± 0.15 1.55 ± 0.10 1.60 ± 0.20 1.70 ± 0.15	0 0 0 0	0 0 0 0	1,000 1,000 1,000 1,000 1,000	4,000 4,000 4,000 4,000 4,000
GO HB HD HF JB	1812 1825 1825 1825 2220	$\begin{array}{c} 2.50 \pm 0.20 \\ 1.10 \pm 0.15 \\ 1.30 \pm 0.15 \\ 1.50 \pm 0.15 \\ 1.00 \pm 0.15 \end{array}$	0 0 0 0	0 0 0 0	500 1,000 1,000 1,000 1,000	2,000 4,000 4,000 4,000 4,000
JC JD JE JF JO	2220 2220 2220 2220 2220 2220	$\begin{array}{c} 1.10 \pm 0.15 \\ 1.30 \pm 0.15 \\ 1.40 \pm 0.15 \\ 1.50 \pm 0.15 \\ 2.40 \pm 0.15 \end{array}$	0 0 0 0	0 0 0 0	1,000 1,000 1,000 1,000 500	4,000 4,000 4,000 4,000 2,000
Thickness	Case	Thickness ±	7" Reel	13" Reel	7" Reel	13" Reel
Code	Size	Range (mm)	Paper C	Quantity	Plastic (	Quantity

Package quantity based on finished chip thickness specifications



9

### Table 3 – Chip Capacitor Land Pattern Design Recommendations per IPC–7351

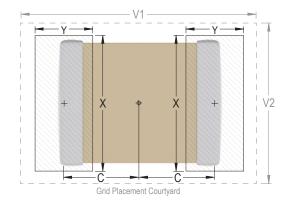
EIA Size Code	Metric Size Code		Maxi	sity Lev mum (M rotrusic	/lost)	)		Media	sity Lev an (Nor rotrusio		)		Minii	sity Lev num (L rotrusio	east)	)
ooue	oode	С	Y	X	V1	V2	С	Y	X	V1	V2	С	Y	X	V1	V2
0402	1005	0.50	0.72	0.72	2.20	1.20	0.45	0.62	0.62	1.90	1.00	0.40	0.52	0.52	1.60	0.80
0603	1608	0.90	1.15	1.10	4.00	2.10	0.80	0.95	1.00	3.10	1.50	0.60	0.75	0.90	2.40	1.20
0805	2012	1.00	1.35	1.55	4.40	2.60	0.90	1.15	1.45	3.50	2.00	0.75	0.95	1.35	2.80	1.70
1206	3216	1.60	1.35	1.90	5.60	2.90	1.50	1.15	1.80	4.70	2.30	1.40	0.95	1.70	4.00	2.00
1210	3225	1.60	1.35	2.80	5.65	3.80	1.50	1.15	2.70	4.70	3.20	1.40	0.95	2.60	4.00	2.90
1210 <sup>1</sup>	3225	1.50	1.60	2.90	5.60	3.90	1.40	1.40	2.80	4.70	3.30	1.30	1.20	2.70	4.00	3.00
1812	4532	2.15	1.60	3.60	6.90	4.60	2.05	1.40	3.50	6.00	4.00	1.95	1.20	3.40	5.30	3.70
2220	5650	2.75	1.70	5.50	8.20	6.50	2.65	1.50	5.40	7.30	5.90	2.55	1.30	5.30	6.60	5.60

<sup>1</sup> Only for capacitance values  $\geq$  22  $\mu$ F

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of EIA 0603, 0805, and 1206 case sizes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC–7351).

Image below based on Density Level B for an EIA 1210 case size.





### **Soldering Process**

#### **Recommended Soldering Technique:**

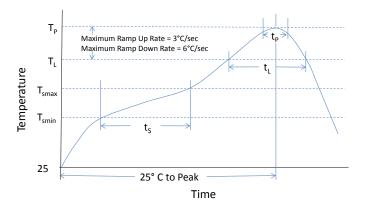
- Solder wave or solder reflow for EIA case sizes 0603, 0805 and 1206
- · All other EIA case sizes are limited to solder reflow only

#### **Recommended Reflow Soldering Profile:**

KEMET's families of surface mount multilayer ceramic capacitors (SMD MLCCs) are compatible with wave (single or dual), convection, IR or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three reflow passes at these conditions.

Profile Feature	Terminati	on Finish
FIONETeature	SnPb	100% Matte Sn
Preheat/Soak		
Temperature Minimum (T <sub>Smin</sub> )	100°C	150°C
Temperature Maximum (T <sub>Smax</sub> )	150°C	200°C
Time (t <sub>s</sub> ) from $T_{Smin}$ to $T_{Smax}$	60 – 120 seconds	60 – 120 seconds
Ramp-Up Rate $(T_L \text{ to } T_P)$	3°C/second maximum	3°C/second maximum
Liquidous Temperature $(T_L)$	183°C	217°C
Time Above Liquidous ( $t_L$ )	60 – 150 seconds	60 – 150 seconds
Peak Temperature (T <sub>P</sub> )	235°C	260°C
Time Within 5°C of Maximum Peak Temperature (t <sub>P</sub> )	20 seconds maximum	30 seconds maximum
Ramp-Down Rate $(T_P \text{ to } T_L)$	6°C/second maximum	6°C/second maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum

Note 1: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.



# Table 4 – Performance & Reliability: Test Methods and Conditions

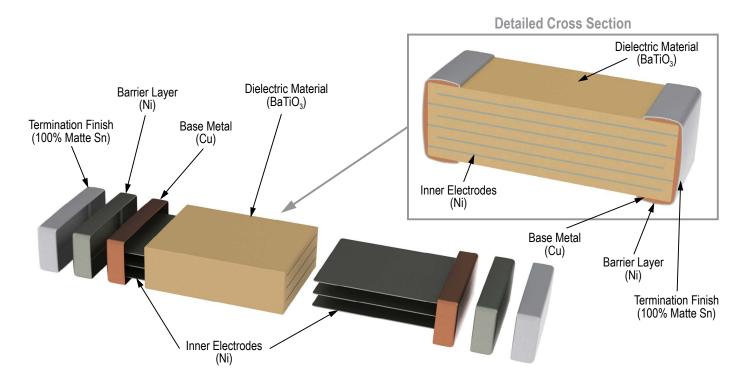
Stress	Reference	Test or Inspection Method
Terminal Strength	JIS-C-6429	Appendix 1, Note: Force of 1.8 kg for 60 seconds.
Board Flex	JIS-C-6429	Appendix 2, Note: Standard termination system – 2.0 mm (minimum) for all except 3 mm for C0G. Flexible termination system – 3.0 mm (minimum).
		Magnification 50 X. Conditions:
Solderability	J-STD-002	a) Method B, 4 hours @ 155°C, dry heat @ 235°C
Solderability	J-51D-002	b) Method B @ 215°C category 3
		c) Method D, category 3 @ 260°C
Temperature Cycling	JESD22 Method JA-104	1,000 Cycles (-55°C to +125°C). Measurement at 24 hours +/- 2 hours after test conclusion.
Biased Humidity	MIL-STD-202 Method 103	Load Humidity: 1,000 hours 85°C/85% RH and rated voltage. Add 100 K ohm resistor. Measurement at 24 hours +/- 2 hours after test conclusion. Low Volt Humidity: 1,000 hours 85°C/85% RH and 1.5 V. Add 100 K ohm resistor. Measurement at 24 hours +/- 2 hours after test conclusion.
Moisture Resistance	MIL-STD-202 Method 106	t = 24 hours/cycle. Steps 7a and 7b not required. Unpowered. Measurement at 24 hours +/- 2 hours after test conclusion.
Thermal Shock	MIL-STD-202 Method 107	-55°C/+125°C. Note: Number of cycles required – 300, maximum transfer time – 20 seconds, dwell time – 15 minutes. Air – Air.
High Temperature Life	MIL-STD-202 Method 108 /EIA-198	1,000 hours at 125°C (85°C for X5R, Z5U and Y5V) with 2 X rated voltage applied.
Storage Life	MIL-STD-202 Method 108	150°C, 0 VDC for 1,000 hours.
Vibration	MIL-STD-202 Method 204	5 g's for 20 min., 12 cycles each of 3 orientations. Note: Use 8" X 5" PCB 0.031" thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10 – 2,000 Hz
Mechanical Shock	MIL-STD-202 Method 213	Figure 1 of Method 213, Condition F.
Resistance to Solvents	MIL-STD-202 Method 215	Add aqueous wash chemical, OKEM Clean or equivalent.

# **Storage and Handling**

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature– reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years of receipt.



# Construction





# **Capacitor Marking (Optional):**

These surface mount multilayer ceramic capacitors are normally supplied unmarked. If required, they can be marked as an extra cost option. Marking is available on most KEMET devices but must be requested using the correct ordering code identifier(s). If this option is requested, two sides of the ceramic body will be laser marked with a "K" to identify KEMET, followed by two characters (per EIA–198 - see table below) to identify the capacitance value. EIA 0603 case size devices are limited to the "K" character only.

Laser marking option is <u>not</u> available on:

- C0G, Ultra Stable X8R and Y5V dielectric devices
- EIA 0402 case size devices
- EIA 0603 case size devices with Flexible Termination option.
- · KPS Commercial and Automotive Grade stacked devices.
- · X7R dielectric products in capacitance values outlined below

EIA Case Size	Metric Size Code	Capacitance
0603	1608	≤ 170 pF
0805	2012	≤ 150 pF
1206	3216	≤ 910 pF
1210	3225	≤ 2,000 pF
1808	4520	≤ 3,900 pF
1812	4532	≤ 6,700 pF
1825	4564	≤ 0.018 µF
2220	5650	≤ 0.027 µF
2225	5664	≤ 0.033 µF

Marking appears in legible contrast. Illustrated below is an example of an MLCC with laser marking of "KA8", which designates a KEMET device with rated capacitance of 100  $\mu$ F. Orientation of marking is vendor optional.



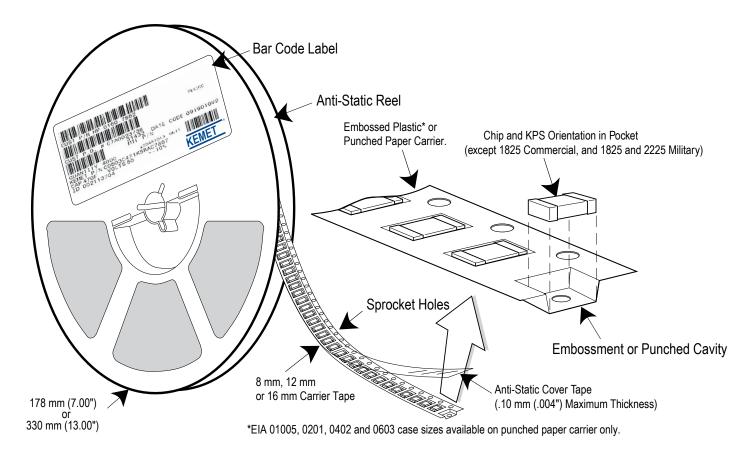
# Capacitor Marking (Optional) cont'd

	Capacitance (pF) For Various Alpha/Numeral Identifiers										
						Numera	al				
Alpha	9	0	1	2	3	4	5	6	7	8	
Character	Capacitance (pF)										
A	0.1	10	10	100	1,000	10,000	100,000	1,000,000	10,000,000	100,000,000	
В	0.11	1.1	11	110	1,100	11,000	110,000	1,100,000	11,000,000	110,000,000	
С	0.12	12	12	120	1,200	12,000	120,000	1,200,000	12,000,000	120,000,000	
D	0.13	13	13	130	1,300	13,000	130,000	1,300,000	13,000,000	130,000,000	
E	0.15	15	15	150	1,500	15,000	150,000	1,500,000	15,000,000	150,000,000	
F	0.16	16	16	160	1,600	16,000	160,000	1,600,000	16,000,000	160,000,000	
G	0.18	18	18	180	1,800	18,000	180,000	1,800,000	18,000,000	180,000,000	
Н	0.2	20	20	200	2,000	20,000	200,000	2,000,000	20,000,000	200,000,000	
J	0.22	22	22	220	2,200	22,000	220,000	2,200,000	22,000,000	220,000,000	
К	0.24	2.4	24	240	2,400	24,000	240,000	2,400,000	24,000,000	240,000,000	
L	0.27	2.7	27	270	2,700	27,000	270,000	2,700,000	27,000,000	270,000,000	
М	0.3	30	30	300	3,000	30,000	300,000	3,000,000	30,000,000	300,000,000	
N	0.33	33	33	330	3,300	33,000	330,000	3,300,000	33,000,000	330,000,000	
Р	0.36	36	36	360	3,600	36,000	360,000	3,600,000	36,000,000	360,000,000	
Q	0.39	39	39	390	3,900	39,000	390,000	3,900,000	39,000,000	390,000,000	
R	0.43	4 3	43	430	4,300	43,000	430,000	4,300,000	43,000,000	430,000,000	
S	0.47	4.7	47	470	4,700	47,000	470,000	4,700,000	47,000,000	470,000,000	
Т	0.51	5.1	51	510	5,100	51,000	510,000	5,100,000	51,000,000	510,000,000	
U	0.56	56	56	560	5,600	56,000	560,000	5,600,000	56,000,000	560,000,000	
V	0.62	62	62	620	6,200	62,000	620,000	6,200,000	62,000,000	620,000,000	
W	0.68	68	68	680	6,800	68,000	680,000	6,800,000	68,000,000	680,000,000	
Х	0.75	75	75	750	7,500	75,000	750,000	7,500,000	75,000,000	750,000,000	
Y	0.82	8 2	82	820	8,200	82,000	820,000	8,200,000	82,000,000	820,000,000	
Z	0.91	9.1	91	910	9,100	91,000	910,000	9,100,000	91,000,000	910,000,000	
а	0.25	2 5	25	250	2,500	25,000	250,000	2,500,000	25,000,000	250,000,000	
b	0.35	3 5	35	350	3,500	35,000	350,000	3,500,000	35,000,000	350,000,000	
d	0.4	4 0	40	400	4,000	40,000	400,000	4,000,000	40,000,000	400,000,000	
e	0.45	4 5	45	450	4,500	45,000	450,000	4,500,000	45,000,000	450,000,000	
f	0.5	50	50	500	5,000	50,000	500,000	5,000,000	50,000,000	500,000,000	
m	0.6	60	60	600	6,000	60,000	600,000	6,000,000	60,000,000	600,000,000	
n	0.7	70	70	700	7,000	70,000	700,000	7,000,000	70,000,000	700,000,000	
t	0.8	80	80	800	8,000	80,000	800,000	8,000,000	80,000,000	800,000,000	
у	0.9	90	90	900	9,000	90,000	900,000	9,000,000	90,000,000	900,000,000	



# Tape & Reel Packaging Information

KEMET offers multilayer ceramic chip capacitors packaged in 8, 12 and 16 mm tape on 7" and 13" reels in accordance with EIA Standard 481. This packaging system is compatible with all tape-fed automatic pick and place systems. See Table 2 for details on reeling quantities for commercial chips.

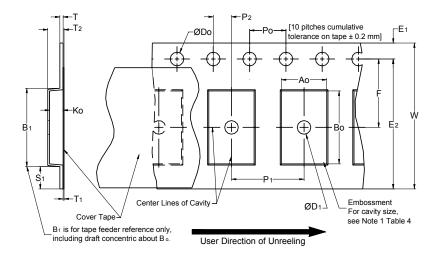


#### Table 5 – Carrier Tape Configuration – Embossed Plastic & Punched Paper (mm)

EIA Case Size	Tape Size (W)*	Pitch (P <sub>1</sub> )*
01005 – 0402	8	2
0603 – 1210	8	4
1805 – 1808	12	4
≥ 1812	12	8
KPS 1210	12	8
KPS 1812 & 2220	16	12
Array 0508 & 0612	8	4

\*Refer to Figures 1 & 2 for W and  $P_1$  carrier tape reference locations. \*Refer to Tables 6 & 7 for tolerance specifications.

# Figure 1 – Embossed (Plastic) Carrier Tape Dimensions



### Table 6 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)									
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum	
8 mm		1.0 (0.039)				25.0 (0.984)				
12 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)		1.75 ±0.10 (0.069 ±0.004) (	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	30 (1.181)	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)	
16 mm		(0.059)								
			Variable Dime	ensions — Mil	limeters (Inch	ies)				
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> ,B <sub>0</sub>	& K <sub>0</sub>	
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)			
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)	Note 5		
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	7.5 ±0.05 (0.138 ±0.002)	12.0 ±0.10 (0.157 ±0.004)	4.6 (0.181)	16.3 (0.642)			

1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.

2. The tape with or without components shall pass around R without damage (see Figure 6).

3. If S<sub>1</sub> < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481 paragraph 4.3 section b).

4. B, dimension is a reference dimension for tape feeder clearance only.

5. The cavity defined by  $A_{\alpha}$ ,  $B_{\alpha}$  and  $K_{\alpha}$  shall surround the component with sufficient clearance that:

(a) the component does not protrude above the top surface of the carrier tape.

(b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.

(c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 3).

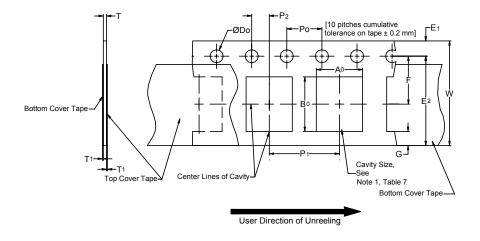
(d) lateral movement of the component is restricted to 0.5 mm maximum for 8 and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 4).

(e) for KPS Series product,  $A_0$  and  $B_0$  are measured on a plane 0.3 mm above the bottom of the pocket.

(f) see Addendum in EIA Standard 481 for standards relating to more precise taping requirements.



# Figure 2 – Punched (Paper) Carrier Tape Dimensions



# Table 7 – Punched (Paper) Carrier Tape Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)									
Tape Size	D <sub>0</sub>	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	T <sub>1</sub> Maximum	G Minimum	R Reference Note 2			
8 mm	1.5 +0.10 -0.0 (0.059 +0.004 -0.0)	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	0.10 (0.004) Maximum	0.75 (0.030)	25 (0.984)			
	Variable Dimensions — Millimeters (Inches)									
Tape Size	Pitch	E2 Minimum	F	P <sub>1</sub>	T Maximum	W Maximum	A <sub>0</sub> B <sub>0</sub>			
8 mm	Half (2 mm)	6.25	3.5 ±0.05	2.0 ±0.05 (0.079 ±0.002)	1.1	8.3 (0.327)	Note 1			
8 mm	Single (4 mm)	(0.246)	(0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	(0.098)	8.3 (0.327)	INOTE 1			

1. The cavity defined by  $A_{\alpha}$ ,  $B_{\alpha}$  and T shall surround the component with sufficient clearance that:

a) the component does not protrude beyond either surface of the carrier tape.

b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.

c) rotation of the component is limited to 20° maximum (see Figure 3).

d) lateral movement of the component is restricted to 0.5 mm maximum (see Figure 4).

e) see Addendum in EIA Standard 481 for standards relating to more precise taping requirements.

2. The tape with or without components shall pass around R without damage (see Figure 6).



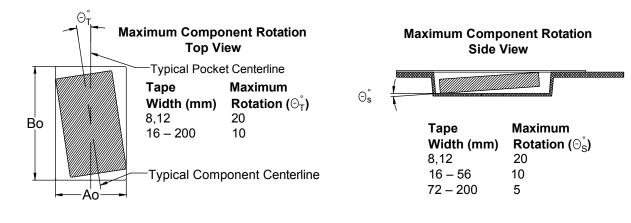
# **Packaging Information Performance Notes**

- 1. Cover Tape Break Force: 1.0 Kg minimum.
- 2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

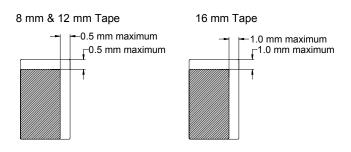
Tape Width	Peel Strength
8 mm	0.1 to 1.0 Newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be  $165^{\circ}$  to  $180^{\circ}$  from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of  $300 \pm 10$  mm/minute. **3. Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards* 556 *and* 624.

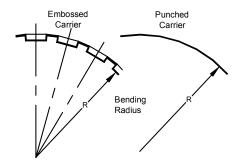
### Figure 3 – Maximum Component Rotation



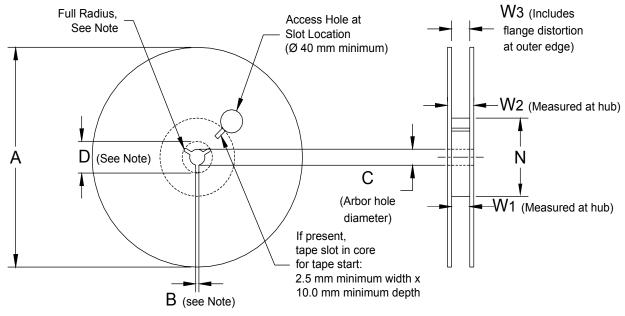
# Figure 4 – Maximum Lateral Movement



# Figure 5 – Bending Radius



# Figure 6 – Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

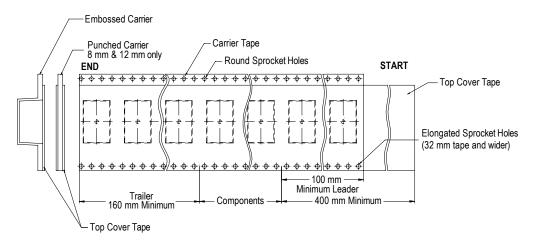
# Table 8 – Reel Dimensions

Metric will govern

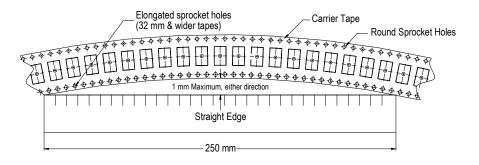
	Constant Dimensions — Millimeters (Inches)								
Tape Size	А	B Minimum	С	D Minimum					
8 mm	178 ±0.20								
12 mm	(7.008 ±0.008) or	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)					
16 mm	330 ±0.20 (13.000 ±0.008)		()						
	Variable Dimensions — Millimeters (Inches)								
Tape Size	Tape Size N Minimum		W <sub>2</sub> Maximum	W <sub>3</sub>					
8 mm		8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)						
12 mm	50 (1.969)	12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference					
16 mm		16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)						



# Figure 7 – Tape Leader & Trailer Dimensions

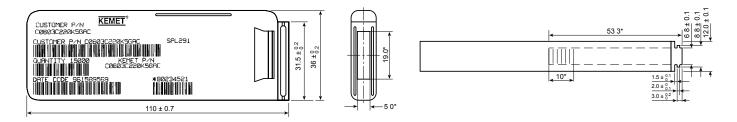


# Figure 8 – Maximum Camber



# Bulk Cassette Packaging (Ceramic Chips Only)

Meets Dimensional Requirements IEC–286 and EIAJ 7201 Unit mm \*Reference



# **Capacitor Dimensions for Bulk Cassette**

Cassette Packaging - Millimeters

EIA Size Code	Metric Size Code	L Length	W Width	B Bandwidth	S Separation Minimum	T Thickness	Number of Pieces/Cassette
0402	1005	1.0 ±0.05	0.5 ±0.05	0.2 to 0.4	0.3	0.5 ±0.05	50,000
0603	1608	1.6 ±0.07	0.8 ±0.07	0.2 to 0.5	0.7	0.8 ±0.07	15,000

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C1023\_X7R\_AUTO\_SMD • 7/24/2014 20

Surface Mount Multilayer Ceramic Chip Capacitors (SMD MLCCs) – X7R Dielectric, 6.3 – 250 VDC (Automotive Grade)



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22

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